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# FQA9P25

#### 250V P-Channel MOSFET

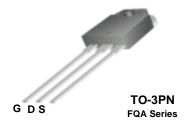
#### **General Description**

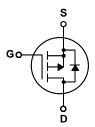
These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand a high energy pulse in the avalanche and commutation modes. These devices are well suited for high efficiency switching DC/DC converters.

#### **Features**

- -10.5A, -250V,  $R_{DS(on)} = 0.62\Omega$  @V<sub>GS</sub> = -10 V Low gate charge ( typical 29 nC)
- Low Crss (typical 27 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

| Symbol                            | Parameter  |          | FQA9P25     | Units |  |
|-----------------------------------|--|----------|-------------|-------|--|
| V <sub>DSS</sub>                  | Drain-Source Voltage   |          | -250        | V     |  |
| I <sub>D</sub>                    | Drain Current - Continuous (T <sub>C</sub> = 25°C) - Continuous (T <sub>C</sub> = 100°C) |          | -10.5       | A     |  |
|                                   |  |          | -6.6        | A     |  |
| I <sub>DM</sub>                   | Drain Current - Pulsed   | (Note 1) | -42         | А     |  |
| $V_{GSS}$                         | Gate-Source Voltage  |          | ± 30        | V     |  |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy   | (Note 2) | 650         | mJ    |  |
| I <sub>AR</sub>                   | Avalanche Current  | (Note 1) | -10.5       | A     |  |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy  | (Note 1) | 15          | mJ    |  |
| dv/dt                             | Peak Diode Recovery dv/dt  | (Note 3) | -5.5        | V/ns  |  |
| P <sub>D</sub>                    | Power Dissipation (T <sub>C</sub> = 25°C)  |          | 150         | W     |  |
|                                   | - Derate above 25°C  |          | 1.2         | W/°C  |  |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range  |          | -55 to +150 | °C    |  |
| TL                                | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds            |          | 300         | °C    |  |

#### **Thermal Characteristics**

| Symbol          | Parameter                               | Тур  | Max  | Units |
|-----------------|---|------|------|-------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case    |      | 0.83 | °C/W  |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink        | 0.24 |      | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient |      | 40   | °C/W  |

| Symbol  | Parameter   | Test Conditions  |             | Min  | Тур   | Max  | Units |
|---|---|--|-------------|------|-------|------|-------|
| Off Cha   | racteristics  |  |             |      |       |      |       |
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                        | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$                         |             | -250 |       |      | V     |
| ΔBV <sub>DSS</sub><br>/ ΔΤ <sub>J</sub>   | Breakdown Voltage Temperature Coefficient             | $I_D$ = -250 μA, Referenced  | to 25°C     |      | -0.2  |      | V/°C  |
| I <sub>DSS</sub>  | Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = -250 V, V <sub>GS</sub> = 0 V                        |             |      |       | -1   | μΑ    |
|   |   | V <sub>DS</sub> = -200 V, T <sub>C</sub> = 125°C                       | ;           |      |       | -10  | μΑ    |
| I <sub>GSSF</sub>   | Gate-Body Leakage Current, Forward                    | $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$                         |             |      |       | -100 | nA    |
| I <sub>GSSR</sub>   | Gate-Body Leakage Current, Reverse                    | V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V                          |             |      |       | 100  | nA    |
| On Cha  | racteristics  |  |             |      |       |      |       |
| V <sub>GS(th)</sub>   | Gate Threshold Voltage                                | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$                                  |             | -3.0 |       | -5.0 | V     |
| R <sub>DS(on)</sub>   | Static Drain-Source On-Resistance                     | V <sub>GS</sub> = -10 V, I <sub>D</sub> = -5.25 A                      |             |      | 0.48  | 0.62 | Ω     |
| 9 <sub>FS</sub>   | Forward Transconductance                              | $V_{DS} = -40 \text{ V}, I_{D} = -5.25 \text{ A}$                      | (Note 4)    |      | 6.1   |      | S     |
| C <sub>oss</sub>  | Output Capacitance                                    | $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$<br>f = 1.0 MHz         |             |      | 170   | 220  | рF    |
| Dynamic Characteristics  C <sub>iss</sub> Input Capacitance V <sub>DC</sub> = -25 V V <sub>CC</sub> = 0 V |   |  |             |      | 910   | 1180 | pF    |
| C <sub>rss</sub>  | Reverse Transfer Capacitance                          | 1 = 1.0 MH2  |             |      | 27    | 35   | pF    |
| Switchi   | ng Characteristics                                    |  |             |      |       |      |       |
| t <sub>d(on)</sub>  | Turn-On Delay Time                                    | $V_{DD} = -125 \text{ V}, I_{D} = -9.4 \text{ A},$ $R_{G} = 25 \Omega$ |             |      | 20    | 50   | ns    |
| t <sub>r</sub>  | Turn-On Rise Time                                     |  |             |      | 150   | 310  | ns    |
| t <sub>d(off)</sub>   | Turn-Off Delay Time                                   |  |             |      | 45    | 100  | ns    |
| t <sub>f</sub>  | Turn-Off Fall Time                                    |  | (Note 4, 5) |      | 65    | 140  | ns    |
| Qg  | Total Gate Charge                                     | $V_{DS} = -200 \text{ V}, I_{D} = -9.4 \text{ A},$                     |             |      | 29    | 38   | nC    |
| $Q_{gs}$  | Gate-Source Charge                                    | V <sub>GS</sub> = -10 V  |             |      | 7.6   |      | nC    |
| $Q_{gd}$  | Gate-Drain Charge                                     | (Note 4, 5)  |             |      | 14    |      | nC    |
| Drain-S   | ource Diode Characteristics a                         | nd Maximum Ratings   | i           |      |       |      |       |
| I <sub>S</sub>  | Maximum Continuous Drain-Source Diode Forward Current |  |             |      | -10.5 | Α    |       |
| I <sub>SM</sub>   | Maximum Pulsed Drain-Source Diode F                   |  |             |      |       | -42  | Α     |
| V <sub>SD</sub>   | Drain-Source Diode Forward Voltage                    | $V_{GS} = 0 \text{ V}, I_{S} = -10.5 \text{ A}$                        |             |      |       | -5.0 | V     |
| t <sub>rr</sub>   | Reverse Recovery Time                                 | $V_{GS} = 0 \text{ V, } I_{S} = -9.4 \text{ A},$                       |             |      | 190   |      | ns    |
| Q <sub>rr</sub>   | Reverse Recovery Charge                               | $dI_F / dt = 100 A/\mu s$ (Note 4)                                     |             |      | 1.45  |      | μC    |

- Notes: 
  1. Repetitive Rating : Pulse width limited by maximum junction temperature 
  2. L = 9.4mH, I<sub>AS</sub> = -10.5A, V<sub>DD</sub> = -50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 
  3. I<sub>SD</sub>  $\le$  -9.4A, di/dt  $\le$  300A/µs, V<sub>DD</sub>  $\le$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 
  4. Pulse Test : Pulse width  $\le$  300µs, Duty cycle  $\le$  2% 
  5. Essentially independent of operating temperature

## **Typical Characteristics**

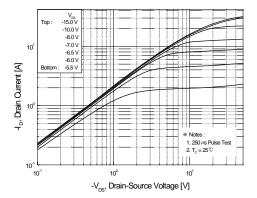


Figure 1. On-Region Characteristics

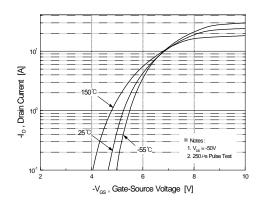


Figure 2. Transfer Characteristics

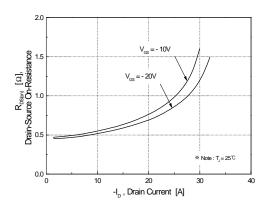


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

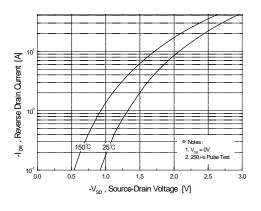


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

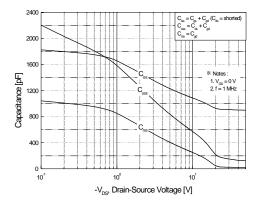


Figure 5. Capacitance Characteristics

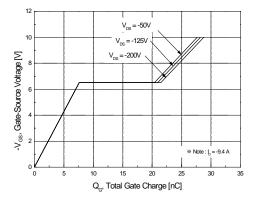
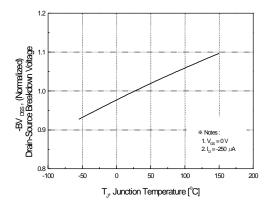


Figure 6. Gate Charge Characteristics

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### Typical Characteristics (Continued)



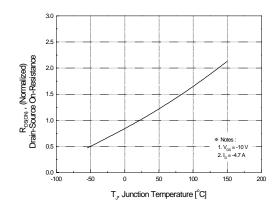
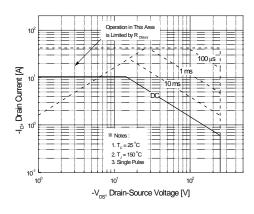


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



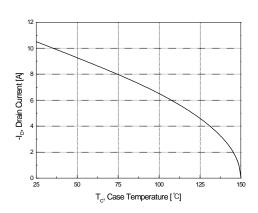


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

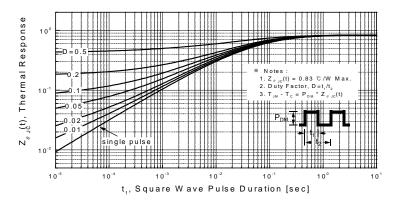
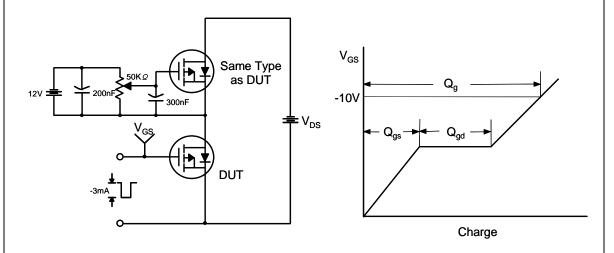


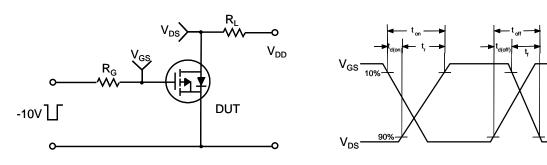
Figure 11. Transient Thermal Response Curve

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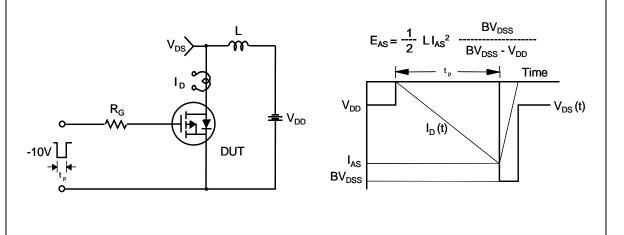
#### **Gate Charge Test Circuit & Waveform**



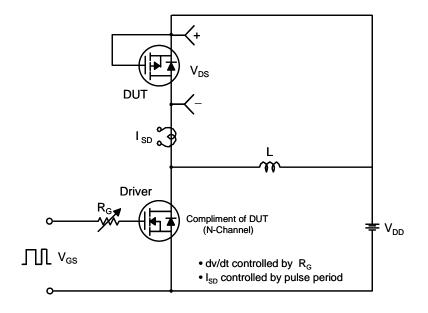
#### **Resistive Switching Test Circuit & Waveforms**

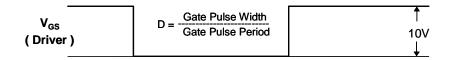


#### **Unclamped Inductive Switching Test Circuit & Waveforms**

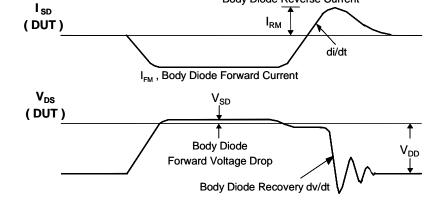


#### Peak Diode Recovery dv/dt Test Circuit & Waveforms





**Body Diode Reverse Current** 



# **Mechanical Dimensions** TO-3PN ø3.30 3.10 15,80 15,40 (R0.50) -5.20 4.80 18.90 18,50 (1.85) -2,20 1.80 2.60 2.20 3,20 2.80 20.30 19.70 **⊕** Ø0.55**⋈** 1.20 5.45 5.45 (R0,50)

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